



Material Content Data Sheet



Sales Product Name	TLE7181EM			Issued	25. September 2017			
MA#	MA000978512							
Package	PG-SSOP-24-4			Weight*	150.88 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.244	2.81	2.81	28131	28131
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8915	
wire	non noble metal	copper	7440-50-8	54.617	36.20	37.14	362002	371474
	noble metal	gold	7440-57-5	0.537	0.36	0.36	3556	3556
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.11		1136
encapsulation	plastics	epoxy resin	-	7.886	5.23		52271	
	inorganic material	silicondioxide	60676-86-0	77.663	51.47	56.81	514753	568160
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19294	19294
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.295	0.20		1958	
	noble metal	silver	7440-22-4	0.886	0.59	0.79	5874	7832
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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